



National Standards Authority of Ireland
Údarás um Chaighdeáin Náisiúnta na hÉireann

STANDARD RECOMMENDATION

S.R. TR 62258-7:2007

ICS 31.080.99

SEMICONDUCTOR DIE PRODUCTS -- PART

7: XML SCHEMA FOR DATA EXCHANGE

(IEC/TR 62258-7:2007 (EQV))

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I.S. CLC/TR 62258-7:2007

TECHNICAL REPORT

CLC/TR 62258-7

RAPPORT TECHNIQUE

TECHNISCHER BERICHT

October 2007

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English version

**Semiconductor die products -
Part 7: XML schema for data exchange
(IEC/TR 62258-7:2007)**

Produits à puce de semi-conducteur -
Partie 7: Schéma d'échange
de données en XML
(CEI/TR 62258-7:2007)

Halbleiter-Chip-Erzeugnisse -
Teil 7: XML-Schema
für den Datenaustausch
(IEC/TR 62258-7:2007)

This Technical Report was approved by CENELEC on 2007-09-01.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1887/DTR, future edition 1 of IEC/TR 62258-7, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC Parallel Unique Acceptance Procedure and was approved by CENELEC as CLC/TR 62258-7 on 2007-09-01.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the Technical Report IEC/TR 62258-7:2007 was approved by CENELEC as a Technical Report without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	Series	International Electrotechnical Vocabulary	–	–
IEC 62258-1	– ¹⁾	Semiconductor die products - Part 1: Requirements for procurement and use	EN 62258-1	2005 ²⁾
IEC 62258-2	– ¹⁾	Semiconductor die products - Part 2: Exchange data formats	EN 62258-2	2005 ²⁾
IEC/TR 62258-4	– ¹⁾	Semiconductor die products - Part 4: Questionnaire for die users and suppliers	CLC/TR 62258-4	2007 ²⁾
IEC 62258-5	– ¹⁾	Semiconductor die products - Part 5: Requirements for information concerning electrical simulation	EN 62258-5	2006 ²⁾
IEC 62258-6	– ¹⁾	Semiconductor die products - Part 6: Requirements for information concerning thermal simulation	EN 62258-6	2006 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.



IEC/TR 62258-7

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TECHNICAL REPORT

**Semiconductor die products –
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TECHNICAL REPORT

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Part 7: XML schema for data exchange**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –**Part 7: XML schema for data exchange****FOREWORD**

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IEC 62258-7, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
47/1887/DTR	47/1897/RVC

Full information on the voting for the approval of this Technical Report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62258 series, under the general title *Semiconductor die products*, can be found on the IEC website. Further parts may be added as required.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organizations that helped prepare this report included the ESPRIT ENCAST and IST ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

SEMICONDUCTOR DIE PRODUCTS –

Part 7: XML schema for data exchange

1 Scope

IEC/TR 62258-7, which is a technical report, has been developed to facilitate the production, supply and use of semiconductor die products, including:

- wafers;
- singulated bare die;
- die and wafers with attached connection structures;
- minimally or partially encapsulated die and wafers.

This report contains an XML schema that describes the elements needed for data exchange and that will allow the implementation of the requirements of IEC 62258-1, IEC 62258-5 and IEC 62258-6, as well as providing an exchange structure that is complementary to those defined in IEC 62258-2. It is also complementary to and compatible with the questionnaire in IEC/TR 62258-4.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary*

IEC 62258-1: *Semiconductor die products – Part 1: Requirements for procurement and use*

IEC 62258-2: *Semiconductor die products – Part 2: Exchange data formats*

IEC/TR 62258-4: *Semiconductor die products – Part 4: Questionnaire for die users and suppliers*

IEC 62258-5: *Semiconductor die products – Part 5 Requirements for information concerning electrical simulation*

IEC 62258-6: *Semiconductor die products – Part 6 Requirements for information concerning thermal simulation*

3 Terms and definitions

For the purposes of this document, relevant terms, which are defined in IEC 60050, together with additional terms and acronyms as given in IEC 62258-1, apply.

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